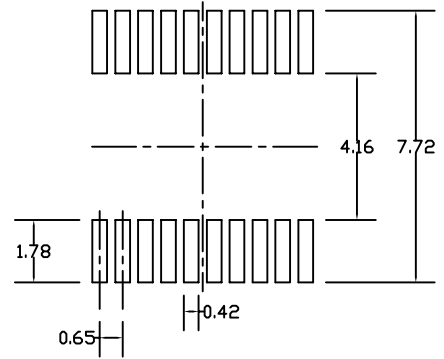
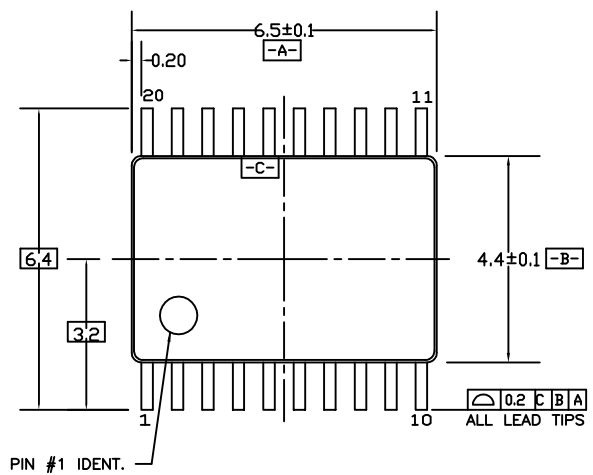
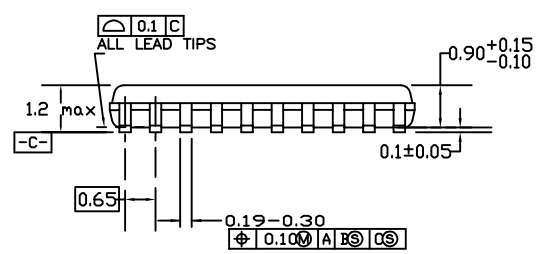


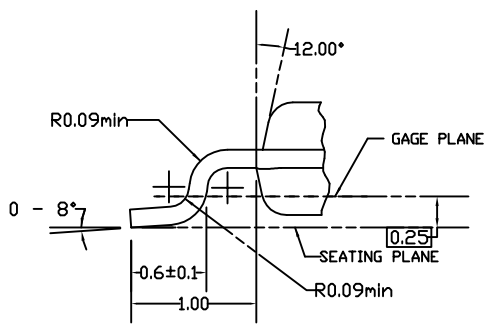
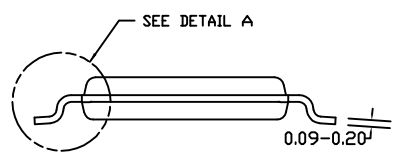
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	REVISE & REDRAW DN PRO/E PER CURRENT STD; CORRECT DET CALLOUT FROM D TO A	11105	08/29/95	MS/
D1	CHANGED TO GPSP/DRAWING ADDED NOTES B, C & D, ADDED MOLDED BODY ANGLE DIM, CHANGED TITLE		21-7-98	FEITAN



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REVD1

APPROVALS	DATE	<b>FAIRCHILD</b> SEMICONDUCTOR	Bayan Lepas, FIZ, 11900, Penang, Malaysia.
DRAWN FEITAN	21-7-98		
DFTG. CHK.		20LD, TSSOP, JEDEC MO-153, 4.4MM WIDE	
ENGR. CHK.			
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	N/A	C	MKT-MTC20
INCH DIMS	DO NOT SCALE DRAWING	REV	D1
		SHEET 1 of 1	